Assignee: Intel Corporation

REMARKS

This responds to the Office Action mailed on April 14, 2004.

Claims 1 and 8 are amended. Claims 1-26 are now pending in this application.

Applicant Interview Summary

Applicant would like to thank Examiner Asok K. Sarkar for the telephone interview with Applicant's Representative, Viet Tong, on April 2, 2004. Non-receipt of the initialed 1449 Forms from the Information Disclosure Statement filed December 30, 2002 was discussed. At Examiner Sarkar's request, Applicant agreed to fax a copy of said Information Disclosure Statement for the Examiner's consideration.

<u>Information Disclosure Statements</u>

Applicant received the initialed 1449 Forms from the Information Disclosure Statement filed on December 11, 2003. However, one of the documents listed on page 2 of the 1449 Form, JP-62-004351, was not initialed.

Additionally, Applicant has not received the initialed 1449 Form for the Supplemental Information Disclosure Statement filed on March 18, 2004.

Applicant respectfully requests that a copy of the 1449 Forms, listing all references that were submitted with the Information Disclosure Statement filed on December 11, 2003, and the Supplemental Information Disclosure Statement filed on March 18, 2004, marked as being considered and initialed by the Examiner, be returned with the next official communication.

§103 Rejection of the Claims

Claims 1-4, 6, 7, and 9 were rejected under 35 USC § 103(a) as being unpatentable over Bertolet (U.S. 5,844,317).

Independent claim 1 is amended. As amended, claim 1 recites elements that Applicant is unable to find in Bertolet. For example, Applicant is unable to find in Bertolet "an interfacial metal layer deposited over said active surface of said microelectronic die, said interfacial metal layer having a plurality of conductive elements including at least one single conductive element

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF

Assignee: Intel Corporation

that is conductively coupled to multiple bond pads". Therefore, Applicant requests that the rejection of claim 1 be reconsidered and withdrawn and that claim 1 and dependent claims 2-4, 6, 7, and 9 be allowed.

Claim 5 was rejected under 35 USC § 103(a) as being unpatentable over Bertolet in view of Perino (U.S. 6,621,155).

Dependent claim 5 depends on claim 1. In view of the amendment to claim 1, Applicant is unable to find in Bertolet and Perino all of the elements of claim 5, which recites the elements of claim 1. For example, Applicant is unable to find in Bertolet and Perino "an interfacial metal layer deposited over said active surface of said microelectronic die, said interfacial metal layer having a plurality of conductive elements including at least one single conductive element that is conductively coupled to multiple bond pads". Accordingly, Applicant requests that the rejection of claim 5 be reconsidered and withdrawn and that claim 5 be allowed.

Allowable Subject Matter

Claims 10-26 were allowed. Applicant acknowledges the allowance of claims 10-26.

Claim 8 was objected to as being dependent upon a rejected base claim, but was indicated to be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. Claim 8 is rewritten in independent form. Thus, Applicant requests that the objection to claim 8 be reconsidered and withdrawn and that claim 8 be allowed.

Serial Number: 09/845881 Filing Date: April 30, 2001

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF

Assignee: Intel Corporation

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's representative ((612) 373-6969) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

QUAT T. VU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Attorneys for Intel Corporation

P.O. Box 2938

Minneapolis, Minnesota 55402

(612) 373-6969

Date	6.	14.01	{
			-

Anne M. Richards

Viet V. Tong Reg. No. 45,416

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 14 day of June 2004.

Name Signature